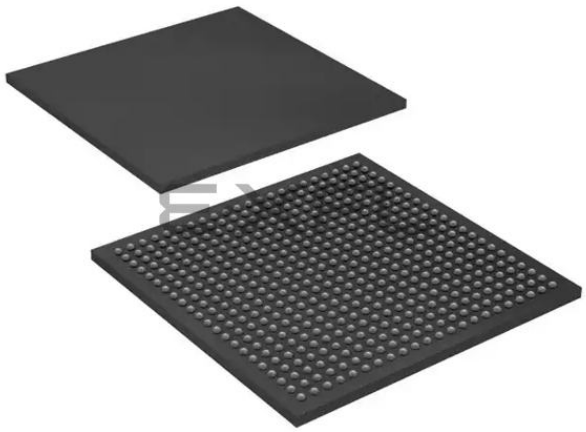

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Details	
Product Status	Active
Number of LABs/CLBs	3491
Number of Logic Elements/Cells	55856
Total RAM Bits	2396160
Number of I/O	324
Number of Gates	-
Voltage - Supply	0.97V ~ 1.03V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce55f23c8l

Cyclone IV Device Family Speed Grades

Table 1–5 lists the Cyclone IV GX devices speed grades.

Table 1–5. Speed Grades for the Cyclone IV GX Device Family

Device	F169	F324	F484	F672	F896
EP4CGX15	C6, C7, C8, I7	—	—	—	—
EP4CGX22	C6, C7, C8, I7	C6, C7, C8, I7	—	—	—
EP4CGX30	C6, C7, C8, I7	C6, C7, C8, I7	C6, C7, C8, I7	—	—
EP4CGX50	—	—	C6, C7, C8, I7	C6, C7, C8, I7	—
EP4CGX75	—	—	C6, C7, C8, I7	C6, C7, C8, I7	—
EP4CGX110	—	—	C7, C8, I7	C7, C8, I7	C7, C8, I7
EP4CGX150	—	—	C7, C8, I7	C7, C8, I7	C7, C8, I7

Table 1–6 lists the Cyclone IV E devices speed grades.

Table 1–6. Speed Grades for the Cyclone IV E Device Family *(1), (2)*

Device	E144	M164	M256	U256	F256	F324	U484	F484	F780
EP4CE6	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	—	—
EP4CE10	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	—	—
EP4CE15	C8L, C9L, I8L C6, C7, C8, I7	I7N	C7N, I7N	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	C8L, C9L, I8L C6, C7, C8, I7, A7	—
EP4CE22	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	—	—
EP4CE30	—	—	—	—	—	A7N	—	C8L, C9L, I8L C6, C7, C8, I7, A7	C8L, C9L, I8L C6, C7, C8, I7
EP4CE40	—	—	—	—	—	A7N	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	C8L, C9L, I8L C6, C7, C8, I7
EP4CE55	—	—	—	—	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7	C8L, C9L, I8L C6, C7, C8, I7
EP4CE75	—	—	—	—	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7	C8L, C9L, I8L C6, C7, C8, I7
EP4CE115	—	—	—	—	—	—	—	C8L, C9L, I8L C7, C8, I7	C8L, C9L, I8L C7, C8, I7

Notes to Table 1–6:

(1) C8L, C9L, and I8L speed grades are applicable for the 1.0-V core voltage.

(2) C6, C7, C8, I7, and A7 speed grades are applicable for the 1.2-V core voltage.

Table 5–2. GCLK Network Connections for EP4CGX30, EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 Devices (1), (2) (Part 4 of 4)

GCLK Network Clock Sources	GCLK Networks																												
	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29
DPCLK17	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	—	—	—	—	—	—	—	—	—

Notes to Table 5–2:

(1) EP4CGX30 information in this table refers to only EP4CGX30 device in F484 package.

(2) PLL_1, PLL_2, PLL_3, and PLL_4 are general purpose PLLs while PLL_5, PLL_6, PLL_7, and PLL_8 are multipurpose PLLs.

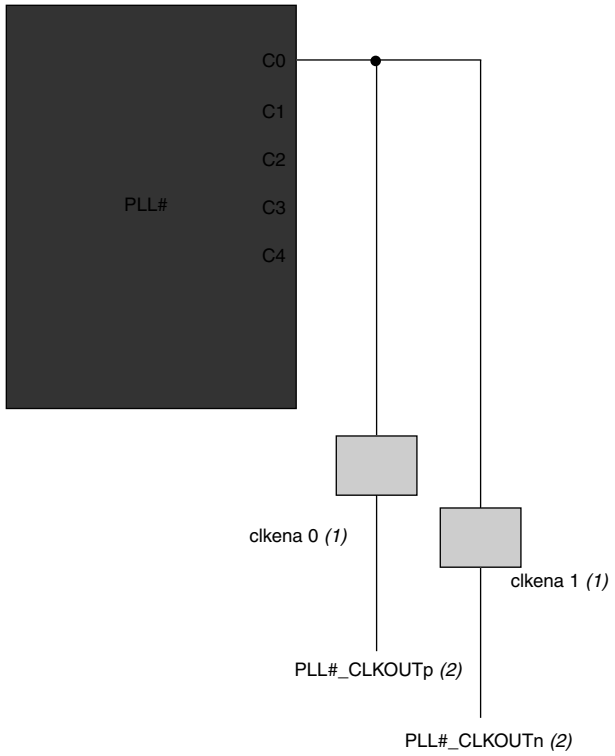
(3) PLL_7 and PLL_8 are not available in EP4CXGX30, EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices in F484 package.

Table 5–3. GCLK Network Connections for Cyclone IV E Devices (1) (Part 1 of 3)

GCLK Network Clock Sources	GCLK Networks																			
	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19
CLK1	—	✓	✓	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
CLK2/DIFFCLK_1p	—	✓	—	✓	✓	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
CLK3/DIFFCLK_1n	✓	—	—	✓	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
CLK4/DIFFCLK_2p	—	—	—	—	—	✓	—	✓	—	✓	—	—	—	—	—	—	—	—	—	—
CLK5/DIFFCLK_2n	—	—	—	—	—	—	✓	✓	—	—	—	—	—	—	—	—	—	—	—	—
CLK6/DIFFCLK_3p	—	—	—	—	—	—	✓	—	✓	✓	—	—	—	—	—	—	—	—	—	—
CLK7/DIFFCLK_3n	—	—	—	—	—	✓	—	—	✓	—	—	—	—	—	—	—	—	—	—	—
CLK8/DIFFCLK_5n (2)	—	—	—	—	—	—	—	—	—	—	✓	—	✓	—	✓	—	—	—	—	—
CLK9/DIFFCLK_5p (2)	—	—	—	—	—	—	—	—	—	—	—	✓	✓	—	—	—	—	—	—	—
CLK10/DIFFCLK_4n (2)	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	✓	—	—	—	—	—
CLK11/DIFFCLK_4p (2)	—	—	—	—	—	—	—	—	—	—	✓	—	—	✓	—	—	—	—	—	—
CLK12/DIFFCLK_7n (2)	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	—	✓
CLK13/DIFFCLK_7p (2)	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	✓	—	—
CLK14/DIFFCLK_6n (2)	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	✓

Figure 5–11 shows the external clock outputs for PLLs.

Figure 5–11. External Clock Outputs for PLLs



Notes to Figure 5–11:

(1) These external clock enable signals are available only when using the ALTCLKCTRL megafunction.

(2) PLL#_CLKOUTp and PLL#_CLKOUTn pins are dual-purpose I/O pins that you can use as one single-ended clock output or one differential clock output. When using both pins as single-ended I/Os, one of them can be the clock output while the other pin is configured as a regular user I/O.

Each pin of a differential output pair is 180° out of phase. The Quartus II software places the NOT gate in your design into the I/O element to implement 180° phase with respect to the other pin in the pair. The clock output pin pairs support the same I/O standards as standard output pins.

To determine which I/O standards are supported by the PLL clock input and output pins, refer to the *Cyclone IV Device I/O Features* chapter.

Cyclone IV PLLs can drive out to any regular I/O pin through the GCLK. You can also use the external clock output pins as GPIO pins if external PLL clocking is not required.

Each Cyclone IV I/O bank has a VREF bus to accommodate voltage-referenced I/O standards. Each VREF pin is the reference source for its V_{REF} group. If you use a V_{REF} group for voltage-referenced I/O standards, connect the VREF pin for that group to the appropriate voltage level. If you do not use all the V_{REF} groups in the I/O bank for voltage-referenced I/O standards, you can use the VREF pin in the unused voltage-referenced groups as regular I/O pins. For example, if you have SSTL-2 Class I input pins in I/O bank 1 and they are all placed in the VREFB1N[0] group, VREFB1N[0] must be powered with 1.25 V, and the remaining VREFB1N[1..3] pins (if available) are used as I/O pins. If multiple V_{REF} groups are used in the same I/O bank, the VREF pins must all be powered by the same voltage level because the VREF pins are shorted together within the same I/O bank.

When VREF pins are used as regular I/Os, they have higher pin capacitance than regular user I/O pins. This has an impact on the timing if the pins are used as inputs and outputs.

For more information about VREF pin capacitance, refer to the pin capacitance section in the *Cyclone IV Device Datasheet* chapter.

For information about how to identify V_{REF} groups, refer to the Cyclone IV **Device Pin-Out** files or the **Quartus II Pin Planner** tool.

Table 6–4 and Table 6–5 summarize the number of VREF pins in each I/O bank for the Cyclone IV device family.

Table 6–4. Number of VREF Pins Per I/O Bank for Cyclone IV E Devices (Part 1 of 2)

Device	EP4CE6			EP4CE10			EP4CE15						EP4CE22			EP4CE30			EP4CE40				EP4CE55			EP4CE75			EP4CE115	
I/O Bank *(1)*	144-EQPF	256-UBGA	256-FBGA	144-EQPF	256-UBGA	256-FBGA	144-EQPF	164-MBGA	256-MBGA	256-UBGA	256-FBGA	484-FBGA	144-EQPF	256-UBGA	256-FBGA	324-FBGA	484-FBGA	780-FBGA	324-FBGA	484-UBGA	484-FBGA	780-FBGA	484-UBGA	484-FBGA	780-FBGA	484-UBGA	484-FBGA	780-FBGA	484-FBGA	780-FBGA
1	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
2	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
3	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
4	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
5	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
6	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
7	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3

Figure 6–16. RSDS, Mini-LVDS, or PPDS Interface with External Resistor Network on the Top and Bottom I/O Banks *(1)*

Note to Figure 6–16:

(1) R_S and R_P values are pending characterization.

A resistor network is required to attenuate the output voltage swing to meet RSDS, mini-LVDS, and PPDS specifications when using emulated transmitters. You can modify the resistor network values to reduce power or improve the noise margin.

The resistor values chosen must satisfy Equation 6–1.

Equation 6–1. Resistor Network

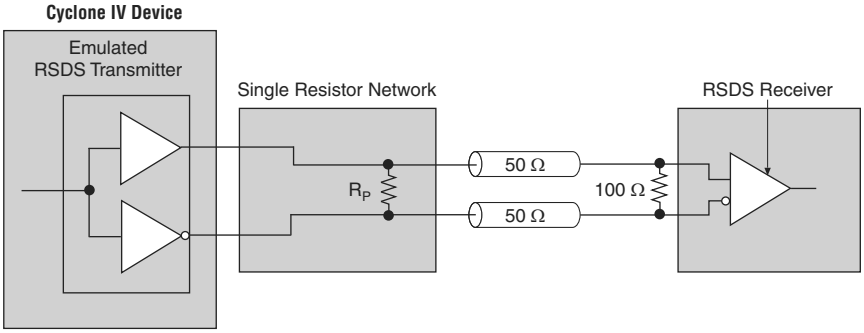
$$\frac{R_S \times \frac{R_P}{2}}{R_S + \frac{R_P}{2}} = 50\ \Omega$$

Altera recommends that you perform simulations using Cyclone IV devices IBIS models to validate that custom resistor values meet the RSDS, mini-LVDS, or PPDS requirements.

It is possible to use a single external resistor instead of using three resistors in the resistor network for an RSDS interface, as shown in Figure 6–17. The external single-resistor solution reduces the external resistor count while still achieving the required signaling level for RSDS. However, the performance of the single-resistor solution is lower than the performance with the three-resistor network.

Figure 6–17 shows the RSDS interface with a single resistor network on the top and bottom I/O banks.

Figure 6–17. RSDS Interface with Single Resistor Network on the Top and Bottom I/O Banks *(1)*



Note to Figure 6–17:

(1) R_P value is pending characterization.

LVPECL I/O Support in Cyclone IV Devices

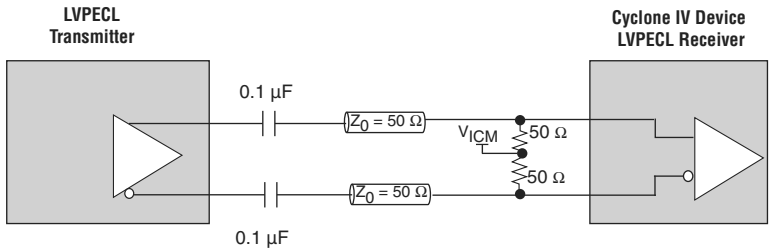
The LVPECL I/O standard is a differential interface standard that requires a 2.5-V V_{CCIO}. This standard is used in applications involving video graphics, telecommunications, data communications, and clock distribution. Cyclone IV devices support the LVPECL input standard at the dedicated clock input pins only. The LVPECL receiver requires an external 100-Ω termination resistor between the two signals at the input buffer.

For the LVPECL I/O standard electrical specification, refer to the *Cyclone IV Device Datasheet* chapter.

AC coupling is required when the LVPECL common mode voltage of the output buffer is higher than the Cyclone IV devices LVPECL input common mode voltage.

Figure 6–18 shows the AC-coupled termination scheme. The 50-Ω resistors used at the receiver are external to the device. DC-coupled LVPECL is supported if the LVPECL output common mode voltage is in the Cyclone IV devices LVPECL input buffer specification (refer to Figure 6–19).

Figure 6–18. LVPECL AC-Coupled Termination *(1)*

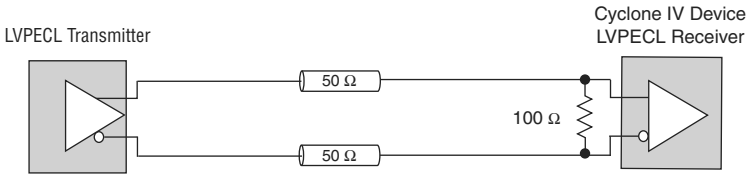


Note to Figure 6–18:

(1) The LVPECL AC-coupled termination is applicable only when an Altera FPGA transmitter is used.

Figure 6–19 shows the LVPECL DC-coupled termination.

Figure 6–19. LVPECL DC-Coupled Termination *(1)*



Note to Figure 6–19:

(1) The LVPECL DC-coupled termination is applicable only when an Altera FPGA transmitter is used.

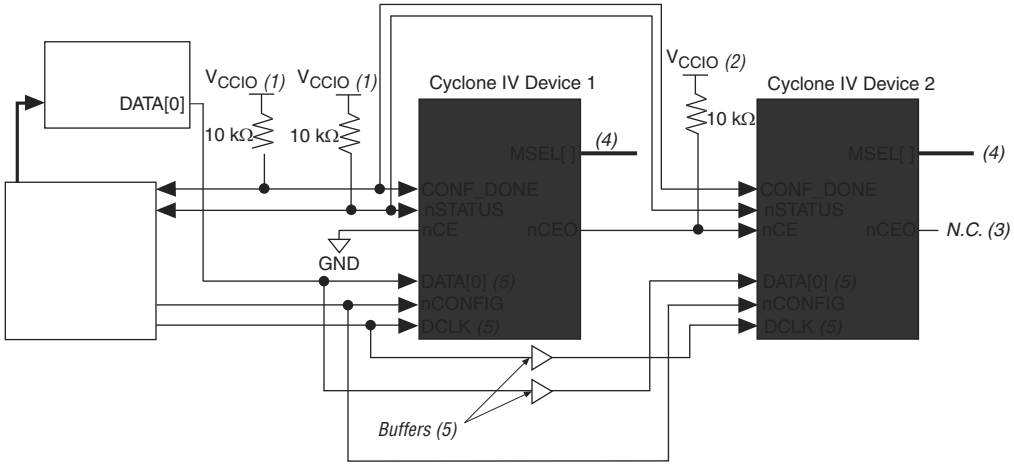
To ensure DCLK and DATA[0] are not left floating at the end of configuration, the MAX II device must drive them either high or low, whichever is convenient on your board. The DATA[0] pin is available as a user I/O pin after configuration. In the PS scheme, the DATA[0] pin is tri-stated by default in user mode and must be driven by the external host device. To change this default option in the Quartus II software, select the **Dual-Purpose Pins** tab of the **Device and Pin Options** dialog box.

The configuration clock (DCLK) speed must be below the specified system frequency to ensure correct configuration. No maximum DCLK period exists, which means you can pause configuration by halting DCLK for an indefinite amount of time.

The external host device can also monitor CONF_DONE and INIT_DONE to ensure successful configuration. The CONF_DONE pin must be monitored by the external device to detect errors and to determine when programming is complete. If all configuration data is sent, but CONF_DONE or INIT_DONE has not gone high, the external device must reconfigure the target device.

Figure 8–14 shows how to configure multiple devices using an external host device. This circuit is similar to the PS configuration circuit for a single device, except that Cyclone IV devices are cascaded for multi-device configuration.

Figure 8–14. Multi-Device PS Configuration Using an External Host



Notes to Figure 8–14:

(1) The pull-up resistor must be connected to a supply that provides an acceptable input signal for all devices in the chain. V_{CC} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host.

(2) Connect the pull-up resistor to the V_{CCIO} supply voltage of the I/O bank in which the nCE pin resides.

(3) The nCEO pin is left unconnected or used as a user I/O pin when it does not feed the nCE pin of another device.

(4) The MSEL pin settings vary for different configuration voltage standards and POR time. To connect the MSEL pins, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9. Connect the MSEL pins directly to V_{CCA} or GND.

(5) All I/O inputs must maintain a maximum AC voltage of 4.1 V. DATA[0] and DCLK must fit the maximum overshoot outlined in Equation 8–1 on page 8–5.

FPP Configuration

The FPP configuration in Cyclone IV devices is designed to meet the increasing demand for faster configuration time. Cyclone IV devices are designed with the capability of receiving byte-wide configuration data per clock cycle.

You can perform FPP configuration of Cyclone IV devices with an intelligent host, such as a MAX II device or microprocessor with flash memory. If your system already contains a CFI flash memory, you can use it for the Cyclone IV device configuration storage as well. The MAX II PFL feature in MAX II devices provides an efficient method to program CFI flash memory devices through the JTAG interface and the logic to control configuration from the flash memory device to the Cyclone IV device.

For more information about the PFL, refer to *AN 386: Using the Parallel Flash Loader with the Quartus II Software*.

FPP configuration is supported in EP4CGX30 (only for F484 package), EP4CGX50, EP4CGX75, EP4CGX110, EP4CGX150, and all Cyclone IV E devices.

The FPP configuration is not supported in E144 package of Cyclone IV E devices.

Cyclone IV devices do not support enhanced configuration devices for FPP configuration.

FPP Configuration Using an External Host

FPP configuration using an external host provides a fast method to configure Cyclone IV devices. In the FPP configuration scheme, you can use an external host device to control the transfer of configuration data from a storage device, such as flash memory, to the target Cyclone IV device. You can store configuration data in an **.rbf**, **.hex**, or **.ttf** format. When using the external host, a design that controls the configuration process, such as fetching the data from flash memory and sending it to

EN_ACTIVE_CLK

The EN_ACTIVE_CLK instruction causes the CLKUSR pin signal to replace the internal oscillator as the clock source. When using the EN_ACTIVE_CLK instruction, you must enable the internal oscillator for the clock change to occur. After this instruction is issued, other JTAG instructions can be issued while the CLKUSR pin signal remains as the clock source. The clock source is only reverted back to the internal oscillator by issuing the DIS_ACTIVE_CLK instruction or a POR.

DIS_ACTIVE_CLK

The DIS_ACTIVE_CLK instruction breaks the CLKUSR enable latch set by the EN_ACTIVE_CLK instruction and causes the clock source to revert back to the internal oscillator. After the DIS_ACTIVE_CLK instruction is issued, you must continue to clock the CLKUSR pin for 10 clock cycles.

Changing the Start Boot Address of the AP Flash

In the AP configuration scheme (for Cyclone IV E devices only), you can change the default configuration boot address of the parallel flash memory to any desired address using the APFC_BOOT_ADDR JTAG instruction.

APFC_BOOT_ADDR

The APFC_BOOT_ADDR instruction is for Cyclone IV E devices only and allows you to define a start boot address for the parallel flash memory in the AP configuration scheme.

This instruction shifts in a start boot address for the AP flash. When this instruction becomes the active instruction, the TDI and TDO pins are connected through a 22-bit active boot address shift register. The shifted-in boot address bits get loaded into the 22-bit AP boot address update register, which feeds into the AP controller. The content of the AP boot address update register can be captured and shifted-out of the active boot address shift register from TDO.

The boot address in the boot address shift register and update register are shifted to the right (in the LSB direction) by two bits versus the intended boot address. The reason for this is that the two LSB of the address are not accessible. When this boot address is fed into the AP controller, two 0s are attached in the end as LSB, thereby pushing the shifted-in boot address to the left by two bits, which become the actual AP boot address the AP controller gets.

If you have enabled the remote update feature, the APFC_BOOT_ADDR instruction sets the boot address for the factory configuration only.

The APFC_BOOT_ADDR instruction is retained after reconfiguration while the system board is still powered on. However, you must reprogram the instruction whenever you restart the system board.

☞ WYSIWYG is an optimization technique that performs optimization on a VQM (Verilog Quartus Mapping) netlist in the Quartus II software.

Error Detection Block

Table 9–3 lists the types of CRC detection to check the configuration bits.

Table 9–3. Types of CRC Detection to Check the Configuration Bits

First Type of CRC Detection	Second Type of CRC Detection
■ CRAM error checking ability (32-bit CRC) during user mode, for use by the CRC_ERROR pin. ■ There is only one 32-bit CRC value. This value covers all the CRAM data.	■ 16-bit CRC embedded in every configuration data frame. ■ During configuration, after a frame of data is loaded into the device, the pre-computed CRC is shifted into the CRC circuitry. ■ Simultaneously, the CRC value for the data frame shifted-in is calculated. If the pre-computed CRC and calculated CRC values do not match, nSTATUS is set low. ■ Every data frame has a 16-bit CRC. Therefore, there are many 16-bit CRC values for the whole configuration bit stream. ■ Every device has a different length of configuration data frame.

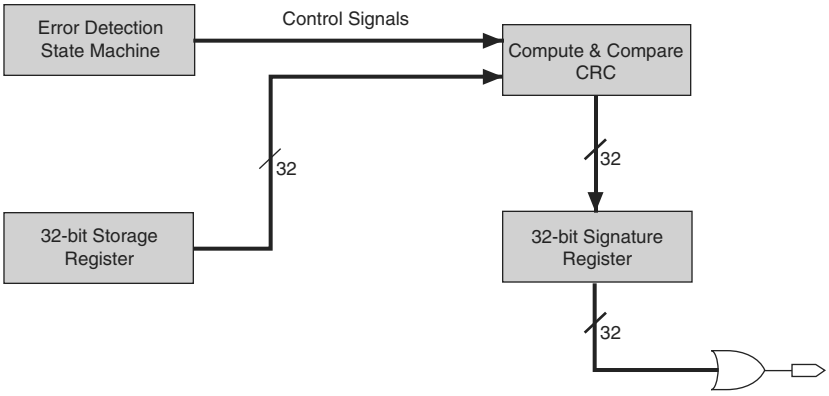
This section focuses on the first type—the 32-bit CRC when the device is in user mode.

Error Detection Registers

There are two sets of 32-bit registers in the error detection circuitry that store the computed CRC signature and pre-calculated CRC value. A non-zero value on the signature register causes the CRC_ERROR pin to set high.

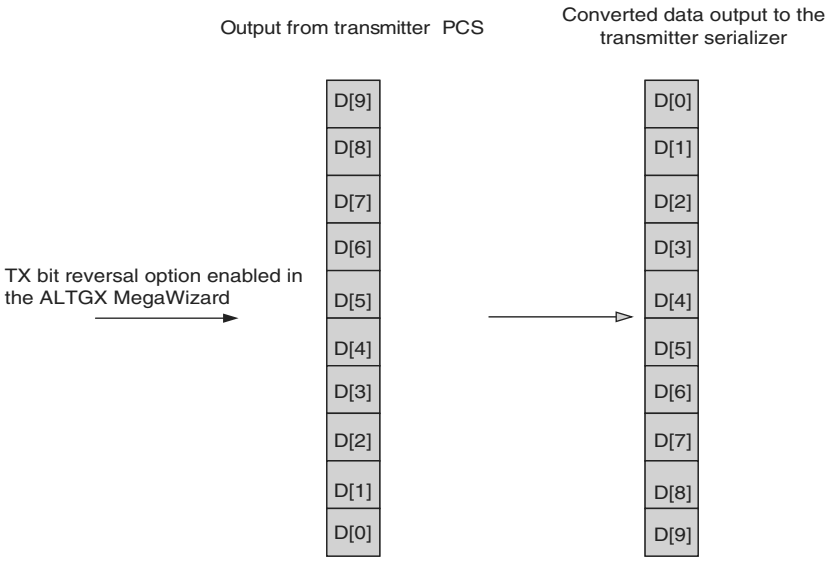
Figure 9–1 shows the block diagram of the error detection block and the two related 32-bit registers: the signature register and the storage register.

Figure 9–1. Error Detection Block Diagram



- Bit reversal—reverses the transmit bit order from LSB-to-MSB (default) to MSB-to-LSB at the input to the serializer. For example, input data to serializer `D[7..0]` is rewired to `D[0..7]` for 8-bit data width, and `D[9..0]` is rewired to `D[0..9]` for 10-bit data width. Figure 1–10 shows the transmitter bit reversal feature.

Figure 1–10. Transmitter Bit Reversal Operation in Basic Single-Width Mode



- Input bit-flip—reverses the bit order at a byte level at the input of the transmitter phase compensation FIFO. For example, if the 16-bit parallel transmitter data at the `tx_datain` port is '10111100 10101101' (16'hBCAD), selecting this option reverses the input data to the transmitter phase compensation FIFO to '00111101 10110101' (16'h3DB5).
- Bit-slip control—delays the data transmission by a number of specified bits to the serializer with the `tx_bitslipboundaryselect` port. For usage details, refer to the "Transmit Bit-Slip Control" on page 1–76.

Serializer

The serializer converts the low-speed parallel 8-bit or 10-bit data from the transmitter PCS to high-speed serial data for the transmitter output buffer. The serializer operates with a high-speed clock at half of the serial data rate. The serializer transmission sequence is LSB to MSB.

Table 1–4 lists the synchronization state machine parameters for the word aligner in this mode.

Table 1–4. Synchronization State Machine Parameters

Parameter	Allowed Values
Number of erroneous code groups received to lose synchronization	1–64
Number of continuous good code groups received to reduce the error count by one	1–256

After deassertion of the rx_digitalreset signal in automatic synchronization state machine mode, the word aligner starts looking for the synchronization code groups, word alignment pattern or its complement in the received data stream. When the programmed number of valid synchronization code groups or ordered sets are received, the rx_syncstatus signal is driven high to indicate that synchronization is acquired. The rx_syncstatus signal is constantly driven high until the programmed number of erroneous code groups are received without receiving intermediate good groups; after which the rx_syncstatus signal is driven low. The word aligner indicates loss of synchronization (rx_syncstatus signal remains low) until the programmed number of valid synchronization code groups are received again.

In addition to restoring word boundaries, the word aligner supports the following features:

- Programmable run length violation detection—detects consecutive 1s or 0s in the data stream, and asserts run length violation signal (rx_rlv) when a preset run length threshold (maximum number of consecutive 1s or 0s) is detected. The rx_rlv signal in each channel is clocked by its parallel recovered clock and is asserted for a minimum of two recovered clock cycles to ensure that the FPGA fabric clock can latch the rx_rlv signal reliably because the FPGA fabric clock might have phase differences, ppm differences (in asynchronous systems), or both, with the recovered clock. Table 1–5 lists the run length violation circuit detection capabilities.

Table 1–5. Run Length Violation Circuit Detection Capabilities

Supported Data Width	Detector Range		Increment Step Settings
	Minimum	Maximum	
8-bit	4	128	4
10-bit	5	160	5

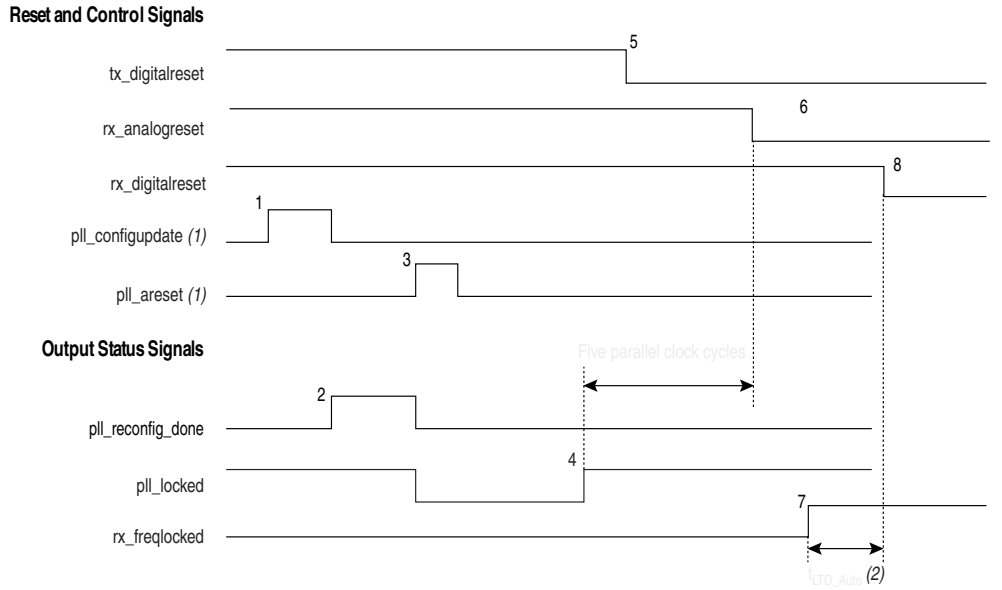
Dynamic Reconfiguration Reset Sequences

When using dynamic reconfiguration in data rate divisions in PLL reconfiguration or channel reconfiguration mode, use the following reset sequences.

Reset Sequence in PLL Reconfiguration Mode

Use the example reset sequence shown in Figure 2–11 when you use the PLL dynamic reconfiguration controller to change the data rate of the transceiver channel. In this example, PLL dynamic reconfiguration is used to dynamically reconfigure the data rate of the transceiver channel configured in Basic ×1 mode with the receiver CDR in automatic lock mode.

Figure 2–11. Reset Sequence When Using the PLL Dynamic Reconfiguration Controller to Change the Data Rate of the Transceiver Channel



Notes to Figure 2–11:

(1) The `pll_configupdate` and `pll_areset` signals are driven by the ALTPLL_RECONFIG megafunction. For more information, refer to *AN 609: Implementing Dynamic Reconfiguration in Cyclone IV GX Devices* and the *Cyclone IV Dynamic Reconfiguration* chapter.

(2) For t_{LTD_Auto} duration, refer to the *Cyclone IV Device Datasheet* chapter.

As shown in Figure 2–11, perform the following reset procedure when using the PLL dynamic reconfiguration controller to change the configuration of the PLLs in the transmitter channel:

1. Assert the `tx_digitalreset`, `rx_analogreset`, and `rx_digitalreset` signals. The `pll_configupdate` signal is asserted (marker 1) by the ALTPLL_RECONFIG megafunction after the final data bit is sent out. The `pll_reconfig_done` signal is asserted (marker 2) to inform the ALTPLL_RECONFIG megafunction that the scan chain process is completed. The ALTPLL_RECONFIG megafunction then asserts the `pll_areset` signal (marker 3) to reset the transceiver PLL.

Table 3–2. Dynamic Reconfiguration Controller Port List (ALTGX_RECONFIG Instance) (Part 3 of 7)

Port Name	Input/ Output	Description
logical_channel_address[n..0]	Input	Enabled by the ALTGX_RECONFIG MegaWizard Plug-In Manager when you enable the **Use 'logical_channel_address' port for Analog controls reconfiguration** option in the **Analog controls** screen. The width of the logical_channel_address port depends on the value you set in the **What is the number of channels controlled by the reconfig controller?** option in the **Reconfiguration settings** screen. This port can be enabled only when the number of channels controlled by the dynamic reconfiguration controller is more than one. Number of channels controlled by the reconfiguration controller — logical_channel_address input port width 2 — logical_channel_address[0] 3–4 — logical_channel_address[1..0] 5–8 — logical_channel_address[2..0] 9–16 — logical_channel_address[3..0]
rx_tx_duplex_sel[1..0]	Input	This is a 2-bit wide signal. You can select this in the **Error checks** screen. The advantage of using this optional port is that it allows you to reconfigure only the transmitter portion of a channel, even if the channel configuration is duplex. For a setting of: ■ rx_tx_duplex_sel[1:0] = 2'b00—the transmitter and receiver portion of the channel is reconfigured. ■ rx_tx_duplex_sel[1:0] = 2'b01—the receiver portion of the channel is reconfigured. ■ rx_tx_duplex_sel[1:0] = 2'b10—the transmitter portion of the channel is reconfigured.

Table 3–2. Dynamic Reconfiguration Controller Port List (ALTGX_RECONFIG Instance) (Part 4 of 7)

<table>
<tr><th>Port Name</th><th>Input/ Output</th><th>Description</th></tr>
<tr><td colspan="3">Analog Settings Control/Status Signals</td></tr>
<tr><td>tx_vodctrl[2..0] (1)</td><td>Input</td><td>This is an optional transmit buffer V_{OD} control signal. It is 3 bits per transmitter channel. The number of settings varies based on the transmit buffer supply setting and the termination resistor setting on the TX Analog screen of the ALTGX MegaWizard Plug-In Manager.

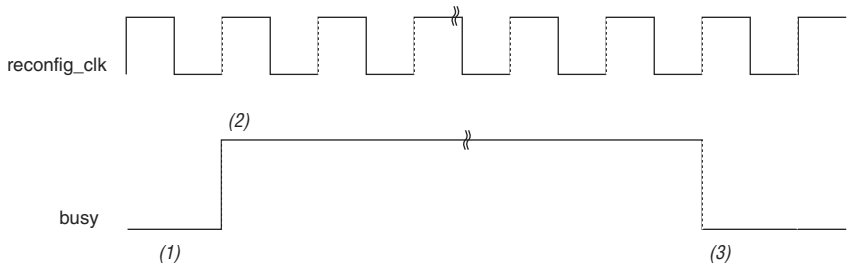
The width of this signal is fixed to 3 bits if you enable either the Use 'logical_channel_address' port for Analog controls reconfiguration option or the Use same control signal for all the channels option in the Analog controls screen. Otherwise, the width of this signal is 3 bits per channel.

The following shows the V_{OD} values corresponding to the tx_vodctrl settings for 100-Ω termination.

For more information, refer to the “Programmable Output Differential Voltage” section of the Cyclone IV GX Device Datasheet chapter.
<table>
<tr><th>tx_vodctrl[2:0]</th><th>Corresponding ALTGX instance settings</th><th>Corresponding V_{OD} settings (mV)</th></tr>
<tr><td>3’b001</td><td>1</td><td>400</td></tr>
<tr><td>3’b010</td><td>2</td><td>600</td></tr>
<tr><td>3’b011</td><td>3</td><td>800</td></tr>
<tr><td>3’b111</td><td>4 (2)</td><td>900 (2)</td></tr>
<tr><td>3’b100</td><td>5</td><td>1000</td></tr>
<tr><td>3’b101</td><td>6</td><td>1200</td></tr>
<tr><td colspan="3">All other values => N/A</td></tr>
</table>
</td></tr>
</table>

Figure 3–3 shows the timing diagram for a offset cancellation process.

Figure 3–3. Dynamic Reconfiguration Signals Transition during Offset Cancellation



Notes to Figure 3–3:

(1) After device power up, the busy signal remains low for the first reconfig_clk cycle.
(2) The busy signal then gets asserted for the second reconfig_clk cycle, when the dynamic reconfiguration controller initiates the offset cancellation process.
(3) The deassertion of the busy signal indicates the successful completion of the offset cancellation process.

Functional Simulation of the Offset Cancellation Process

You must connect the ALTGX_RECONFIG instances to the ALTGX instances in your design for functional simulation. Functional simulation uses a reduced timing model of the dynamic reconfiguration controller. Therefore, the duration of the offset cancellation process is 16 reconfig_clk clock cycles for functional simulation only. The gxb_powerdown signal must not be asserted during the offset cancellation sequence (for functional simulation and silicon).

Dynamic Reconfiguration Modes

When you enable the dynamic reconfiguration feature, you can reconfigure the following portions of each transceiver channel dynamically, without powering down the other transceiver channels or the FPGA fabric of the device:

- Analog (PMA) controls reconfiguration
- Channel reconfiguration
- PLL reconfiguration

Table 3–3 lists the supported dynamic reconfiguration modes for Cyclone IV GX devices.

Table 3–3. Cyclone IV GX Supported Dynamic Reconfiguration Mode (Part 1 of 2)

Dynamic Reconfiguration Supported Mode	Operational Mode			Quartus II Instances			.mif Requirements
	Transmitter Only	Receiver Only	Transmitter and Receiver Only	ALTGX	ALTGX_RECONFIG	ALTPLL_RECONFIG	
Offset Cancellation	—	✓	✓	✓	✓	—	—
Analog (PMA) Controls Reconfiguration	✓	✓	✓	✓	✓	—	—

Table 3–5 describes the rx_dataoutfull[31..0] FPGA fabric-Transceiver channel interface signals.

Table 3–5. rx_dataoutfull[31..0] FPGA Fabric-Transceiver Channel Interface Signal Descriptions (Part 1 of 3)

FPGA Fabric-Transceiver Channel Interface Description	Receive Signal Description (Based on Cyclone IV GX Supported FPGA Fabric-Transceiver Channel Interface Widths)
8-bit FPGA fabric-Transceiver Channel Interface	**The following signals are used in 8-bit 8B/10B modes:**
	rx_dataoutfull[7:0]: 8-bit decoded data (rx_dataout)
	rx_dataoutfull[8]: Control bit (rx_ctrldetect)
	rx_dataoutfull[9]: Code violation status signal (rx_errdetect)
	rx_dataoutfull[10]: rx_syncstatus
	rx_dataoutfull[11]: Disparity error status signal (rx_disperr)
	rx_dataoutfull[12]: Pattern detect status signal (rx_patterndetect)
	rx_dataoutfull[13]: Rate Match FIFO deletion status indicator (rx_rmfifodatadeleted) in non-PCI Express (PIPE) functional modes.
	rx_dataoutfull[14]: Rate Match FIFO insertion status indicator (rx_rmfifodatainserted) in non-PCI Express (PIPE) functional modes.
	rx_dataoutfull[14:13]: PCI Express (PIPE) functional mode (rx_pipestatus)
	rx_dataoutfull[15]: 8B/10B running disparity indicator (rx_runningdisp)
10-bit FPGA fabric-Transceiver Channel Interface	rx_dataoutfull[9:0]: 10-bit un-encoded data (rx_dataout)
	rx_dataoutfull[10]: rx_syncstatus
	rx_dataoutfull[11]: 8B/10B disparity error indicator (rx_disperr)
	rx_dataoutfull[12]: rx_patterndetect
	rx_dataoutfull[13]: Rate Match FIFO deletion status indicator (rx_rmfifodatadeleted) in non-PCI Express (PIPE) functional modes
	rx_dataoutfull[14]: Rate Match FIFO insertion status indicator (rx_rmfifodatainserted) in non-PCI Express (PIPE) functional modes
	rx_dataoutfull[15]: 8B/10B running disparity indicator (rx_runningdisp)

☞ A DC signal is equivalent to 100% duty cycle. For example, a signal that overshoots to 4.3 V can only be at 4.3 V for 65% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 65/10ths of a year.

Table 1–2. Maximum Allowed Overshoot During Transitions over a 10-Year Time Frame for Cyclone IV Devices

Symbol	Parameter	Condition (V)	Overshoot Duration as % of High Time	Unit
V_i	AC Input Voltage	V_I = 4.20	100	%
		V_I = 4.25	98	%
		V_I = 4.30	65	%
		V_I = 4.35	43	%
		V_I = 4.40	29	%
		V_I = 4.45	20	%
		V_I = 4.50	13	%
		V_I = 4.55	9	%
		V_I = 4.60	6	%

Figure 1–1 shows the methodology to determine the overshoot duration. The overshoot voltage is shown in red and is present on the input pin of the Cyclone IV device at over 4.3 V but below 4.4 V. From Table 1–2, for an overshoot of 4.3 V, the percentage of high time for the overshoot can be as high as 65% over a 10-year period. Percentage of high time is calculated as ([delta T]/T) × 100. This 10-year period assumes that the device is always turned on with 100% I/O toggle rate and 50% duty cycle signal. For lower I/O toggle rates and situations in which the device is in an idle state, lifetimes are increased.

Figure 1–1. Cyclone IV Devices Overshoot Duration

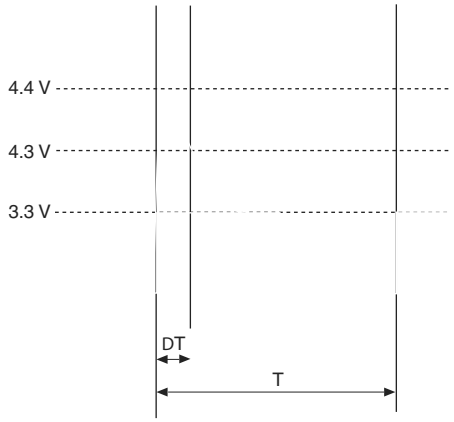


Table 1–4. Recommended Operating Conditions for Cyclone IV GX Devices (Part 2 of 2)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CCA_GXB}	Transceiver PMA and auxiliary power supply	—	2.375	2.5	2.625	V
V_{CCL_GXB}	Transceiver PMA and auxiliary power supply	—	1.16	1.2	1.24	V
V_I	DC input voltage	—	–0.5	—	3.6	V
V_O	DC output voltage	—	0	—	V_{CCIO}	V
T_J	Operating junction temperature	For commercial use	0	—	85	°C
		For industrial use	–40	—	100	°C
t_{RAMP}	Power supply ramp time	Standard power-on reset (POR) *(7)*	50 µs	—	50 ms	—
		Fast POR *(8)*	50 µs	—	3 ms	—
I_{Diode}	Magnitude of DC current across PCI-clamp diode when enabled	—	—	—	10	mA

Notes to Table 1–4:

(1) All VCCA pins must be powered to 2.5 V (even when PLLs are not used) and must be powered up and powered down at the same time.

(2) You must connect V_{CCD_PLL} to V_{CCINT} through a decoupling capacitor and ferrite bead.

(3) Power supplies must rise monotonically.

(4) V_{CCIO} for all I/O banks must be powered up during device operation. Configurations pins are powered up by V_{CCIO} of I/O Banks 3, 8, and 9 where I/O Banks 3 and 9 only support V_{CCIO} of 1.5, 1.8, 2.5, 3.0, and 3.3 V. For fast passive parallel (FPP) configuration mode, the V_{CCIO} level of I/O Bank 8 must be powered up to 1.5, 1.8, 2.5, 3.0, and 3.3 V.

(5) You must set V_{CC_CLKIN} to 2.5 V if you use CLKIN as a high-speed serial interface (HSSI) refclk or as a DIFFCLK input.

(6) The CLKIN pins in I/O Banks 3B and 8B can support single-ended I/O standard when the pins are used to clock left PLLs in non-transceiver applications.

(7) The POR time for Standard POR ranges between 50 and 200 ms. V_{CCINT}, V_{CCA}, and V_{CCIO} of I/O Banks 3, 8, and 9 must reach the recommended operating range within 50 ms.

(8) The POR time for Fast POR ranges between 3 and 9 ms. V_{CCINT}, V_{CCA}, and V_{CCIO} of I/O Banks 3, 8, and 9 must reach the recommended operating range within 3 ms.

ESD Performance

This section lists the electrostatic discharge (ESD) voltages using the human body model (HBM) and charged device model (CDM) for Cyclone IV devices general purpose I/Os (GPIOs) and high-speed serial interface (HSSI) I/Os. Table 1–5 lists the ESD for Cyclone IV devices GPIOs and HSSI I/Os.

Table 1–5. ESD for Cyclone IV Devices GPIOs and HSSI I/Os

Symbol	Parameter	Passing Voltage	Unit
V_{ESDHBM}	ESD voltage using the HBM (GPIOs) *(1)*	± 2000	V
	ESD using the HBM (HSSI I/Os) *(2)*	± 1000	V
V_{ESDCDM}	ESD using the CDM (GPIOs)	± 500	V
	ESD using the CDM (HSSI I/Os) *(2)*	± 250	V

Notes to Table 1–5:

(1) The passing voltage for EP4CGX15 and EP4CGX30 row I/Os is ±1000V.

(2) This value is applicable only to Cyclone IV GX devices.

For more information about the supported maximum clock rate, device and pin planning, IP implementation, and device termination, refer to *Section III: System Performance Specifications* of the *External Memory Interface Handbook*.

Table 1–37 lists the memory output clock jitter specifications for Cyclone IV devices.

Table 1–37. Memory Output Clock Jitter Specifications for Cyclone IV Devices *(1), (2)*

Parameter	Symbol	Min	Max	Unit
Clock period jitter	$t_{JIT(per)}$	–125	125	ps
Cycle-to-cycle period jitter	$t_{JIT(cc)}$	–200	200	ps
Duty cycle jitter	$t_{JIT(duty)}$	–150	150	ps

Notes to Table 1–37:

(1) Memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2 standard.

(2) The clock jitter specification applies to memory output clock pins generated using DDIO circuits clocked by a PLL output routed on a global clock (GCLK) network.

Duty Cycle Distortion Specifications

Table 1–38 lists the worst case duty cycle distortion for Cyclone IV devices.

Table 1–38. Duty Cycle Distortion on Cyclone IV Devices I/O Pins *(1), (2), (3)*

Symbol	C6		C7, I7		C8, I8L, A7		C9L		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

Notes to Table 1–38:

(1) The duty cycle distortion specification applies to clock outputs from the PLLs, global clock tree, and IOE driving the dedicated and general purpose I/O pins.

(2) Cyclone IV devices meet the specified duty cycle distortion at the maximum output toggle rate for each combination of I/O standard and current strength.

(3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

OCT Calibration Timing Specification

Table 1–39 lists the duration of calibration for series OCT with calibration at device power-up for Cyclone IV devices.

Table 1–39. Timing Specification for Series OCT with Calibration at Device Power-Up for Cyclone IV Devices *(1)*

Symbol	Description	Maximum	Units
t_{OCTCAL}	Duration of series OCT with calibration at device power-up	20	µs

Note to Table 1–39:

(1) OCT calibration takes place after device configuration and before entering user mode.